

1 Typical Applications

- Upgrading Legacy Peripherals to USB
- Cellular and Cordless Phone USB data transfer cables and interfaces
- Interfacing MCU/PLD/FPGA based designs to USB
- USB Audio and Low Bandwidth Video data transfer
- PDA to USB data transfer
- USB Smart Card Readers
- USB Instrumentation
- USB Industrial Control
- USB MP3 Player Interface
- USB FLASH Card Reader and Writers
- Set Top Box PC - USB interface
- USB Digital Camera Interface
- USB Hardware Modems
- USB Wireless Modems
- USB Bar Code Readers
- USB Software and Hardware Encryption Dongles

1.1 Driver Support

Royalty free VIRTUAL COM PORT (VCP) DRIVERS for...

- Windows 7 32,64-bit
- Windows XP and XP 64-bit
- Windows Vista and Vista 64-bit
- Windows XP Embedded
- Windows 98, 98SE, ME, 2000, Server 2003, XP and Server 2008
- Windows CE 4.2, 5.0 and 6.0
- Mac OS 8/9, OS-X
- Linux 2.4 and greater

Royalty free D2XX Direct Drivers (USB Drivers + DLL S/W Interface)

- Windows 7 32,64-bit
- Windows XP and XP 64-bit
- Windows Vista and Vista 64-bit
- Windows XP Embedded
- Windows 98, 98SE, ME, 2000, Server 2003, XP and Server 2008
- Windows CE 4.2, 5.0 and 6.0
- Linux 2.4 and greater

The drivers listed above are all available to download for free from FTDI website (www.ftdichip.com). Various 3rd party drivers are also available for other operating systems - see FTDI website (www.ftdichip.com) for details. For driver installation, please refer to the application note AN232B-10.

For driver installation, please refer to <http://www.ftdichip.com/Documents/InstallGuides.htm>

1.2 Part Numbers

Part Number	Package
FT245RQ-xxxx	32 Pin QFN
FT245RL-xxxx	28 Pin SSOP

Note: Packaging codes for xxx is:

-Reel: Taped and Reel, (SSOP is 2,000pcs per reel, QFN is 6,000pcs per reel).

- Tube: Tube packing, 47pcs per tube (SSOP only)

- Tray: Tray packing, 490pcs per tray (QFN only)

For example: FT245RQ-Reel is 6,000pcs taped and reel packing

1.3 USB Compliant

The FT245R is fully compliant with the USB 2.0 specification and has been given the USB-IF Test-ID (TID) 40680005 (Rev B) and 40770019 (Rev C).



2 FT245R Block Diagram

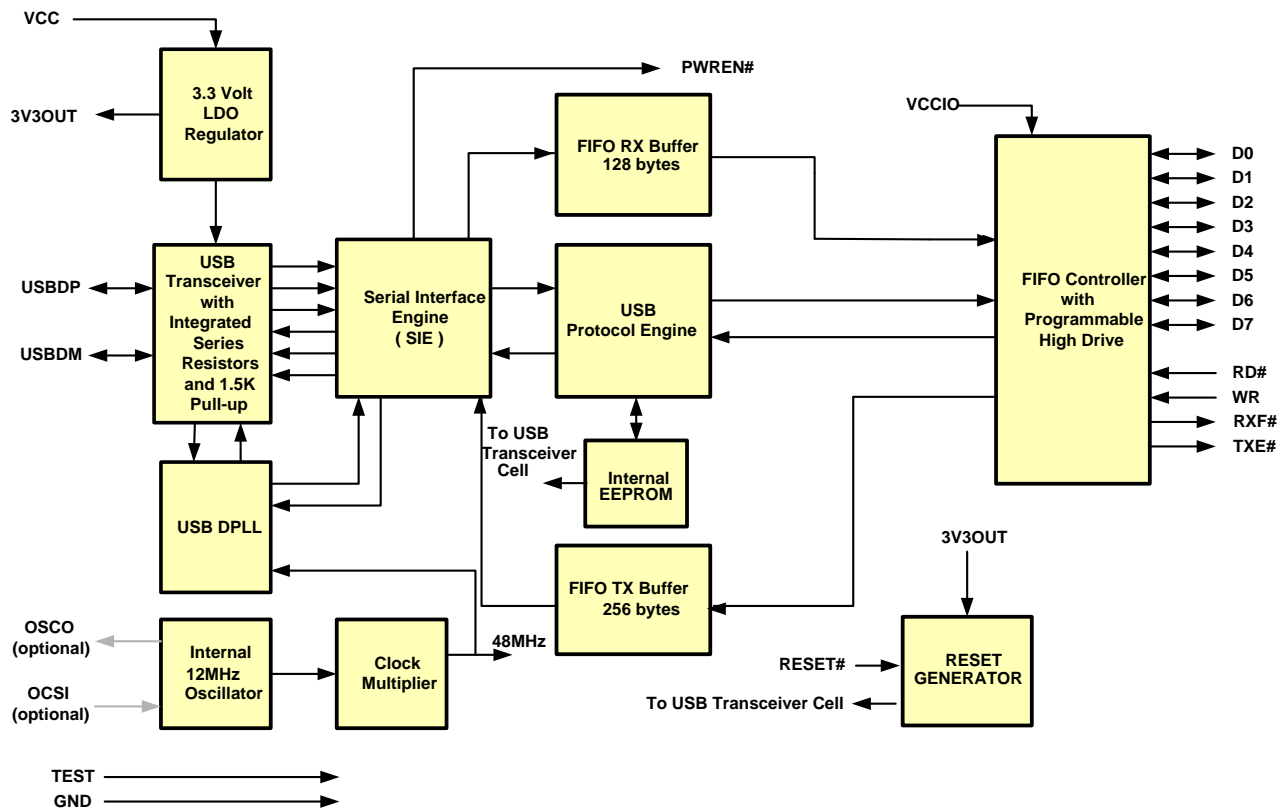


Figure 2.1 FT245R Block Diagram

For a description of each function please refer to Section 4.

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3 Device Pin Out and Signal Description

3.1 28-LD SSOP Package

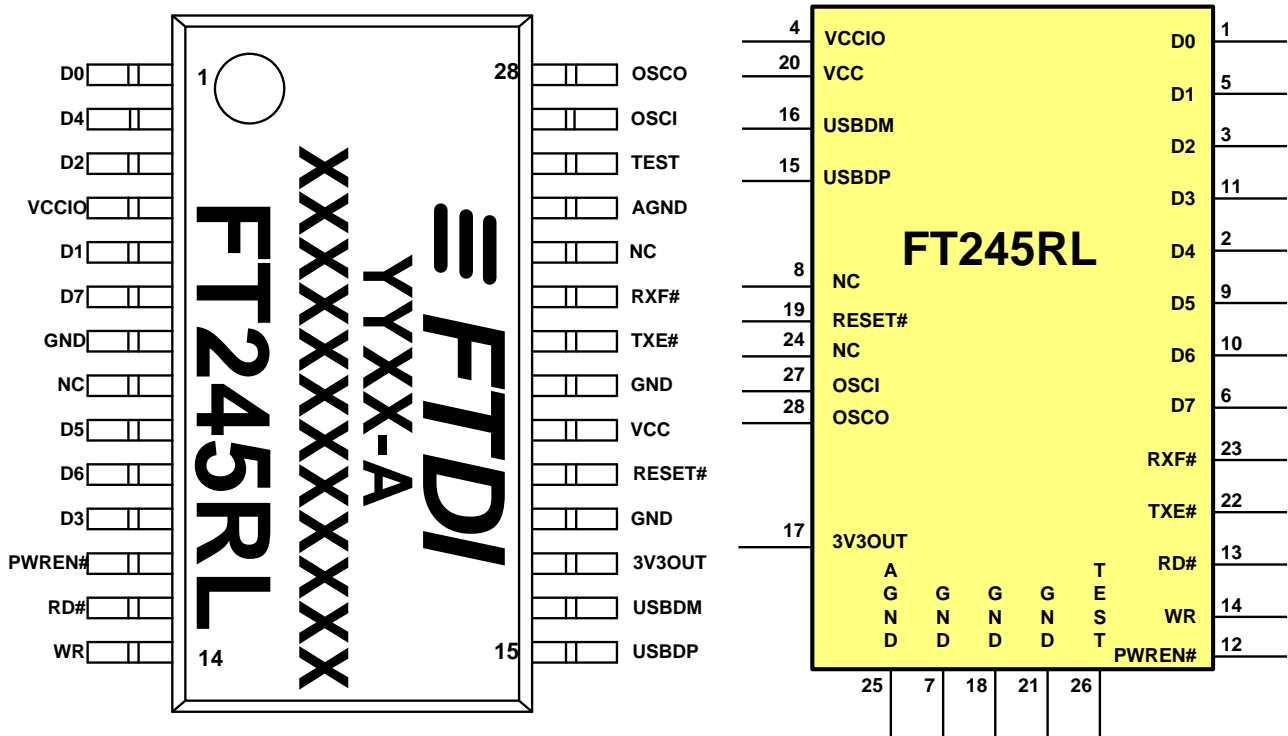


Figure 3.1 SSOP Package Pin Out and Schematic Symbol

3.2 SSOP Package Pin Out Description

Note: The convention used throughout this document for active low signals is the signal name followed by a #

Pin No.	Name	Type	Description
15	USBDP	I/O	USB Data Signal Plus, incorporating internal series resistor and 1.5kΩ pull up resistor to 3.3V.
16	USBDM	I/O	USB Data Signal Minus, incorporating internal series resistor.

Table 3.1 USB Interface Group

Pin No.	Name	Type	Description
4	VCCIO	PWR	+1.8V to +5.25V supply to the FIFO Interface group pins (1...3, 5, 6, 9...14, 22, 23). In USB bus powered designs connect this pin to 3V3OUT pin to drive out at +3.3V levels, or connect to VCC to drive out at 5V CMOS level. This pin can also be supplied with an external +1.8V to +2.8V supply in order to drive outputs at lower levels. It should be noted that in this case this supply should originate from the same source as the supply to VCC. This means that in bus powered designs a regulator which is supplied by the +5V on the USB bus should be used.
7, 18, 21	GND	PWR	Device ground supply pins
17	3V3OUT	Output	+3.3V output from integrated LDO regulator. This pin should be decoupled to ground using a 100nF capacitor. The main use of this pin is to provide the internal +3.3V supply to the USB transceiver cell and the internal 1.5kΩ pull up resistor on USBDP. Up to 50mA can be drawn from this pin to power external logic if required. This pin can also be used to supply the VCCIO pin.
20	VCC	PWR	+3.3V to +5.25V supply to the device core. (see Note 1)

Pin No.	Name	Type	Description
25	AGND	PWR	Device analogue ground supply for internal clock multiplier

Table 3.2 Power and Ground Group

Pin No.	Name	Type	Description
8, 24	NC	NC	No internal connection
19	RESET#	Input	Active low reset pin. This can be used by an external device to reset the FT245R. If not required can be left unconnected, or pulled up to VCC.
26	TEST	Input	Puts the device into IC test mode. Must be tied to GND for normal operation, otherwise the device will appear to fail.
27	OSCI	Input	Input 12MHz Oscillator Cell. Optional – Can be left unconnected for normal operation. (see Note 2)
28	OSCO	Output	Output from 12MHz Oscillator Cell. Optional – Can be left unconnected for normal operation if internal Oscillator is used. (see Note 2)

Table 3.3 Miscellaneous Signal Group

Pin No.	Name	Type	Description
1	D0	I/O	FIFO Data Bus Bit 0
2	D4	I/O	FIFO Data Bus Bit 4
3	D2	I/O	FIFO Data Bus Bit 2
5	D1	I/O	FIFO Data Bus Bit 1
6	D7	I/O	FIFO Data Bus Bit 7
9	D5	I/O	FIFO Data Bus Bit 5
10	D6	I/O	FIFO Data Bus Bit 6
11	D3	I/O	FIFO Data Bus Bit 3
12	PWREN#	Output	Goes low after the device is configured by USB, then high during USB suspend. Can be used to control power to external logic P-Channel logic level MOSFET switch. Enable the interface pull-down option when using the PWREN# pin in this way. Should be pulled to VCCIO with 10kΩ resistor.
13	RD#	Input	Enables the current FIFO data byte on D0...D7 when low. Fetches the next FIFO data byte (if available) from the receive FIFO buffer when RD# goes from high to low. S
14	WR	Input	Writes the data byte on the D0...D7 pins into the transmit FIFO buffer when WR goes from high to low. See Section 3.6 for timing diagram.
22	TXE#	Output	When high, do not write data into the FIFO. When low, data can be written into the FIFO by strobing WR high, then low. During reset this signal pin is tri-state. See Section 3.6 for timing diagram.
23	RXF	Output	When high, do not read data from the FIFO. When low, there is data available in the FIFO which can be read by strobing RD# low, then high again. During reset this signal pin is tri-state.. If the Remote Wakeup option is enabled in the internal EEPROM, during USB suspend mode (PWREN# = 1) RXF# becomes an input. This can be used to wake up the USB host from suspend mode by strobing this pin low for a minimum of 20ms which will cause the device to request a resume on the USB bus.

Table 3.4 FIFO Interface Group (see note 3)
Notes:

1. The minimum operating voltage VCC must be +4.0V (could use VBUS=+5V) when using the internal clock generator. Operation at +3.3V is possible using an external crystal oscillator.
2. For details on how to use an external crystal, ceramic resonator, or oscillator with the FT245R, please refer Section 7.2
3. When used in Input Mode, the input pins are pulled to VCCIO via internal 200kΩ resistors. These pins can be programmed to gently pull low during USB suspend (PWREN# = "1") by setting an option in the internal EEPROM.

3.3 QFN-32 Package

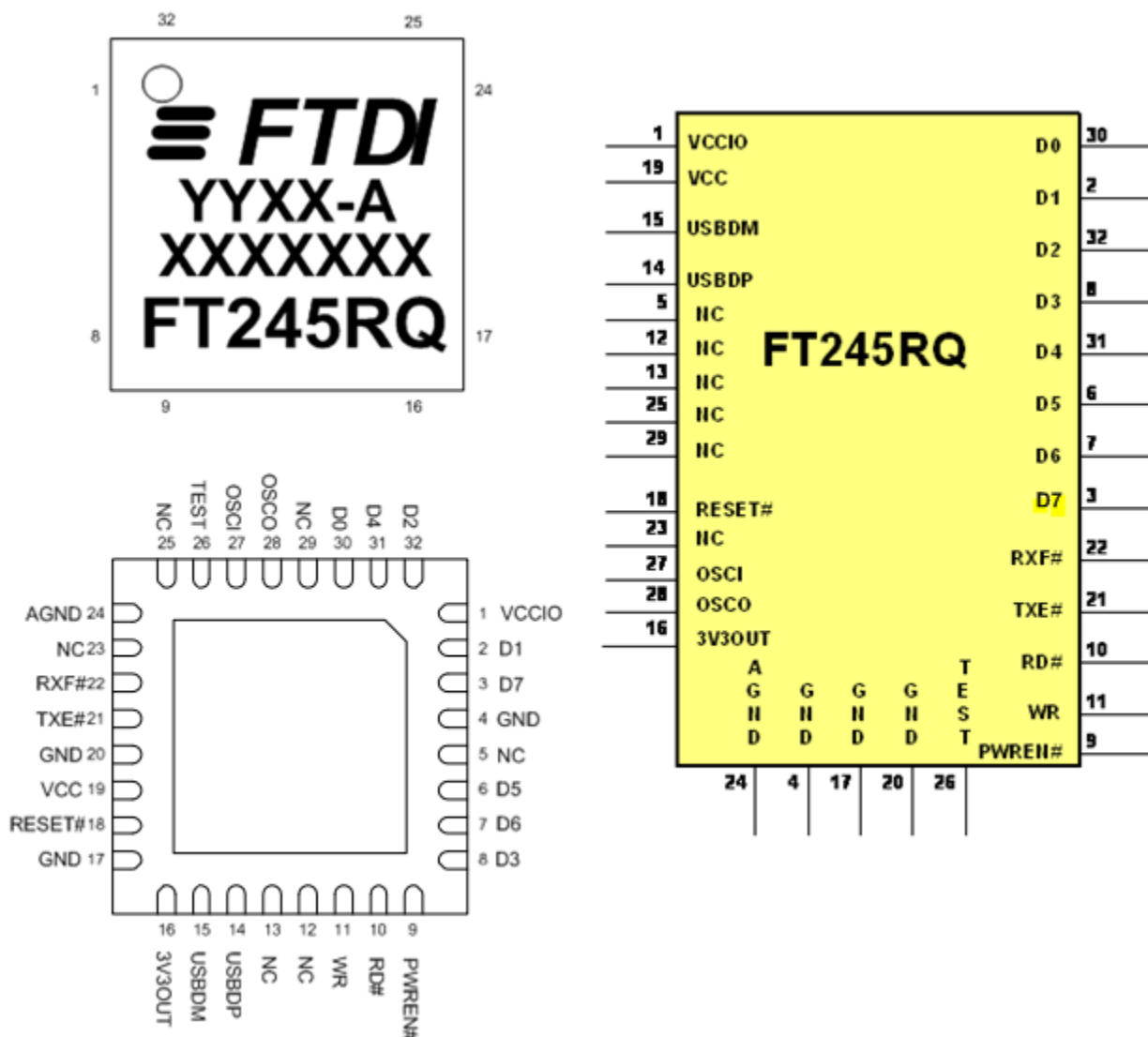


Figure 3.2 QFN-32 Package Pin Out and schematic symbol

3.4 QFN-32 Package Signal Description

Pin No.	Name	Type	Description
14	USBDP	I/O	USB Data Signal Plus, incorporating internal series resistor and 1.5kΩ pull up resistor to +3.3V.
15	USBDM	I/O	USB Data Signal Minus, incorporating internal series resistor.

Table 3.5 USB Interface Group

Pin No.	Name	Type	Description
1	VCCIO	PWR	+1.8V to +5.25V supply for the FIFO Interface group pins (2, 3, 6, 7, 8, 9, 10, 11, 21, 22, 30, 31, 32). In USB bus powered designs connect this pin to 3V3OUT to drive out at +3.3V levels, or connect to VCC to drive out at +5V CMOS level. This pin can also be supplied with an external +1.8V to +2.8V supply in order to drive out at lower levels. It should be noted that in this case this supply should originate from the same source as the supply to VCC. This means that in bus powered designs a regulator which is supplied by the +5V on the USB bus should be used.
4, 17, 20	GND	PWR	Device ground supply pins.
16	3V3OUT	Output	+3.3V output from integrated LDO regulator. This pin should be decoupled

Pin No.	Name	Type	Description
			to ground using a 100nF capacitor. The purpose of this output is to provide the internal +3.3V supply to the USB transceiver cell and the internal 1.5kΩ pull up resistor on USBDP. Up to 50mA can be drawn from this pin to power external logic if required. This pin can also be used to supply the VCCIO pin.
19	VCC	PWR	+3.3V to +5.25V supply to the device core. (see Note 1).
24	AGND	PWR	Device analogue ground supply for internal clock multiplier.

Table 3.6 Power and Ground Group

Pin No.	Name	Type	Description
5, 12, 13, 23, 25, 29	NC	NC	No internal connection. Do not connect.
18	RESET#	Input	Active low reset. Can be used by an external device to reset the FT245R. If not required can be left unconnected, or pulled up to VCC.
26	TEST	Input	Puts the device into IC test mode. Must be tied to GND for normal operation, otherwise the device will appear to fail.
27	OSCI	Input	Input 12MHz Oscillator Cell. Optional – Can be left unconnected for normal operation. (see Note 2).
28	OSCO	Output	Output from 12MHZ Oscillator Cell. Optional – Can be left unconnected for normal operation if internal Oscillator is used. (see Note 2).

Table 3.7 Miscellaneous Signal Group

Pin No.	Name	Type	Description
30	D0	I/O	FIFO Data Bus Bit 0
31	D4	I/O	FIFO Data Bus Bit 4
32	D2	I/O	FIFO Data Bus Bit 2
2	D1	I/O	FIFO Data Bus Bit 1
3	D7	I/O	FIFO Data Bus Bit 7
6	D5	I/O	FIFO Data Bus Bit 5
7	D6	I/O	FIFO Data Bus Bit 6
8	D3	I/O	FIFO Data Bus Bit 3
9	PWREN#	Output	Goes low after the device is configured by USB, then high during USB suspend. Can be used to control power to external logic P-Channel logic level MOSFET switch. Enable the interface pull-down option when using the PWREN# pin in this way. Should be pulled to VCCIO with 10kΩ resistors.
10	RD#	Input	Enables the current FIFO data byte from D0...D7 when low. Fetched the next FIFO data byte (if available) from the receive FIFO buffer when RD# goes from high to low..
11	WR	Input	Writes the data from byte from D0...D7 pins into the transmit FIFO buffer when WR goes from high to low. See section 3.6 for timing diagram.
21	TXE#	Output	When high, do not write data into the FIFO. When low, data can be written into the FIFO by strobing WR high, then low. During reset this signal pin is tri-state. See Section 3.6 for timing diagram.
22	RXF#	Output	When high, do not read data from the FIFO. When low, there is data available in the FIFO which can be read by strobing RD# low, then high again. During reset this signal pin is tri-state.. If the Remote Wakeup option is enabled in the internal EEPROM, during USB suspend mode (PWREN# = 1) RXF# becomes an input. This can be used to wake up the USB host from suspend mode by strobing this pin low for a minimum of 20ms which will cause the device to request a resume on the USB bus.

Table 3.8 FIFO Interface Group (see note 3)
Notes:

1. The minimum operating voltage VCC must be +4.0V (could use VBUS=+5V) when using the internal clock generator. Operation at +3.3V is possible using an external crystal oscillator.
2. For details on how to use an external crystal, ceramic resonator, or oscillator with the FT245R, please refer to Section 7.2
3. When used in Input Mode, the input pins are pulled to VCCIO via internal 200kΩ resistors. These pins can be programmed to gently pull low during USB suspend (PWREN# = "1") by setting an option in the internal EEPROM.

3.5 FT245R FIFO READ Timing Diagrams

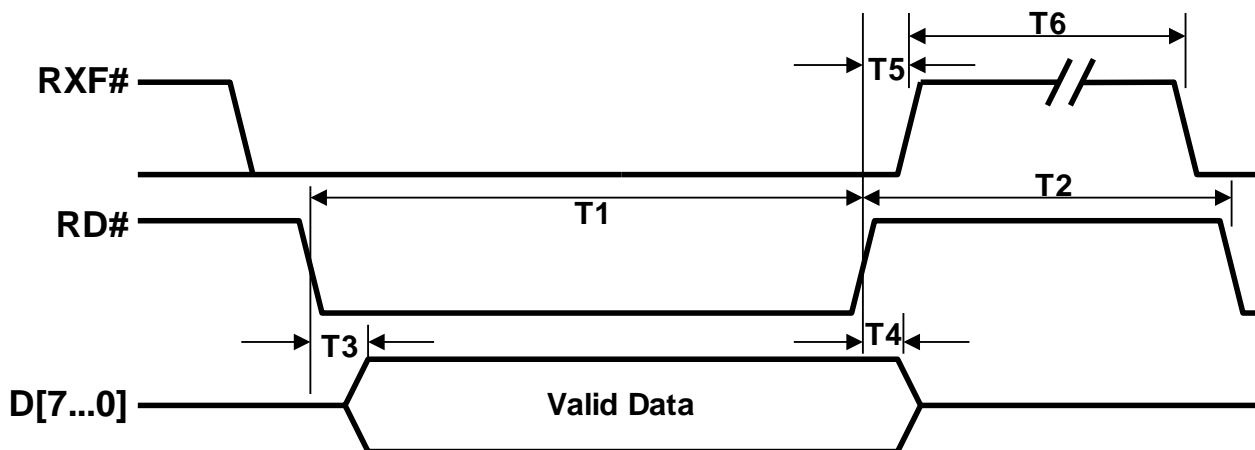


Figure 3.3 FIFO Read Cycle

Time	Description	Minimum	Maximum	Unit
T1	RD# Active Pulse Width	50	-	ns
T2	RD# to RD# Pre-Charge Time	50 + T6	-	ns
T3	RD# Active to Valid Data*	20	50	ns
T4	Valid Data Hold Time from RD# Inactive*	0	-	ns
T5	RD# Inactive to RXF#	0	25	ns
T6	RXF# Inactive After RD Cycle	80	-	ns

Table 3.9 FIFO Read Cycle Timings

*Load = 30pF

3.6 FT245R FIFO WRITE Timing Diagrams

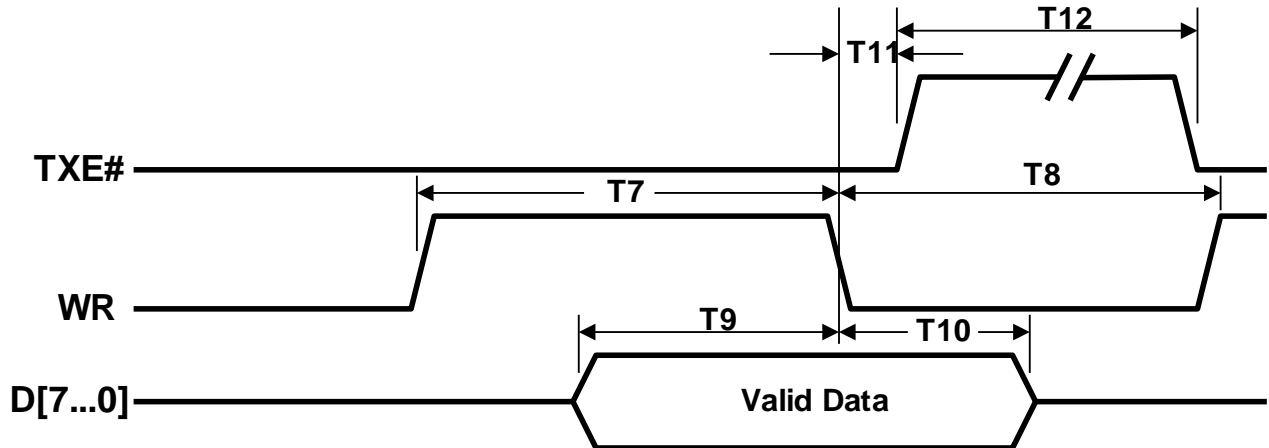


Figure 3.4 FIFO Write Cycle

Time	Description	Minimum	Maximum	Unit
T7	WR Active Pulse Width	50	-	ns
T8	WR to WR Pre-Charge Time	50	-	ns
T9	Valid data setup to WR falling edge*	20	-	ns
T10	Valid Data Hold Time from WR Inactive*	0	-	ns
T11	WR Inactive to TXE#	5	25	ns
T12	TXE# Inactive After WR Cycle	80	-	ns

Table 3.10 FIFO Write Cycle

*Load = 30pF

4 Function Description

The FT245R is a USB to parallel FIFO interface device which simplifies USB to FIFO designs and reduces external component count by fully integrating an external EEPROM, USB termination resistors and an integrated clock circuit which requires no external crystal, into the device. It has been designed to operate efficiently with a USB host controller by using as little as possible of the total USB bandwidth available.

4.1 Key Features

Functional Integration. Fully integrated EEPROM, USB termination resistors, clock generation, AVCC filtering, power-on-reset (POR) and LDO regulator.

Asynchronous Bit Bang Mode. In asynchronous bit-bang mode, the eight FIFO lines can be switched from the regular interface mode to an 8-bit general purpose I/O port. Data packets can be sent to the device and they will be sequentially sent to the interface at a rate controlled by an internal timer (equivalent to the baud rate pre-scaler. This option will be described more fully in a separate application note available from FTDI website (www.ftdichip.com)).

Synchronous Bit Bang Mode. The FT245R supports synchronous bit bang mode. This mode differs from asynchronous bit bang mode in that the interface pins are only read when the device is written to. This makes it easier for the controlling program to measure the response to an output stimulus as the data returned is synchronous to the output data. An application note, AN232R-01, available from FTDI website (www.ftdichip.com) describes this feature.

TDIChip-ID™. The FT245R also includes the new FTDIChip-ID™ security dongle feature. This FTDIChip-ID™ feature allows a unique number to be burnt into each device during manufacture. This number cannot be reprogrammed. This number is only readable over USB and forms a basis of a security dongle which can be used to protect any customer application software being copied. This allows the possibility of using the FT245R in a dongle for software licensing. Further to this, a renewable license scheme can be implemented based on the FTDIChip-ID™ number when encrypted with other information. This encrypted number can be stored in the user area of the FT245R internal EEPROM, and can be decrypted, then compared with the protected FTDIChip-ID™ to verify that a license is valid. Web based applications can be used to maintain product licensing this way. An application note, AN232R-02, available from FTDI website (www.ftdichip.com) describes this feature.

High Output Drive Option. The parallel FIFO interface and the four FIFO handshake pins can be made to drive out at three times the standard signal drive level thus allowing multiple devices to be driven, or devices that require a greater signal drive strength to be interfaced to the FT245R. This option is configured in the internal EEPROM.

Programmable FIFO RX Buffer Timeout. The FIFO RX buffer timeout is used to flush remaining data from the receive buffer. This timeout defaults to 16ms, but is programmable over USB in 1ms increments from 2ms to 255ms, thus allowing the device to be optimised for protocols that require fast response times from short data packets.

Wake Up Function. If USB is in suspend mode, and remote wake up has been enabled in the internal EEPROM (it is enabled by default), the RXF# pin becomes an input. Strobing this pin low for a minimum of 20ms will cause the FT245R to request a resume from suspend on the USB bus. Normally this can be used to wake up the host PC from suspend.

The FT245R is capable of operating at a voltage supply between +3.3V and +5V with a nominal operational mode current of 15mA and a nominal USB suspend mode current of 70µA. This allows greater margin for peripheral designs to meet the USB suspend mode current limit of 2.5mA. An integrated level converter within the FIFO interface allows the FT245R to interface to FIFO logic running at +1.8V, 2.5V, +3.3V or +5V.

4.2 Functional Block Descriptions

The following paragraphs detail each function within the FT245R. Please refer to the block diagram shown in **Figure 2.1**.

Internal EEPROM. The internal EEPROM in the FT245R is used to store USB Vendor ID (VID), Product ID (PID), device serial number, product description string and various other USB configuration descriptors. The FT245R is supplied with the internal EEPROM pre-programmed as described in Section 8. A user area of the internal EEPROM is available to system designers to allow storing additional data. The internal EEPROM descriptors can be programmed in circuit, over USB without any additional voltage requirement. It can be programmed using the FTDI utility software called MPROG and FT_PROG, which can be downloaded from FTDI Utilities on the FTDI website (www.ftdichip.com).

+3.3V LDO Regulator. The +3.3V LDO regulator generates the +3.3V reference voltage for driving the USB transceiver cell output buffers. It requires an external decoupling capacitor to be attached to the 3V3OUT regulator output pin. It also provides +3.3V power to the 1.5k Ω internal pull up resistor on USBDP. The main function of the LDO is to power the USB Transceiver and the Reset Generator Cells rather than to power external logic. However, it can be used to supply external circuitry requiring a +3.3V nominal supply with a maximum current of 50mA.

USB Transceiver. The USB Transceiver Cell provides the USB 1.1 / USB 2.0 full-speed physical interface to the USB cable. The output drivers provide +3.3V level slew rate control signalling, whilst a differential input receiver and two single ended input receivers provide USB data in, Single-Ended-0 (SE0) and USB reset detection conditions respectfully. This function also incorporates the internal USB series termination resistors on the USB data lines and a 1.5k Ω pull up resistor on USBDP.

USB DPLL. The USB DPLL cell locks on to the incoming NRZI USB data and generates recovered clock and data signals for the Serial Interface Engine (SIE) block.

Internal 12MHz Oscillator. The Internal 12MHz Oscillator cell generates a 12MHz reference clock. This provides an input to the x4 Clock Multiplier function. The 12MHz Oscillator is also used as the reference clock for the SIE, USB Protocol Engine and FIFO controller blocks.

Clock Multiplier / Divider. The Clock Multiplier / Divider takes the 12MHz input from the Internal Oscillator function and generates the 48MHz. The 48Mhz clock reference is used by the USB DPLL and the Baud Rate Generator blocks.

Serial Interface Engine (SIE). The Serial Interface Engine (SIE) block performs the parallel to serial and serial to parallel conversion of the USB data. In accordance with the USB 2.0 specification, it performs bit stuffing/un-stuffing and CRC5/CRC16 generation. It also checks the CRC on the USB data stream.

USB Protocol Engine. The USB Protocol Engine manages the data stream from the device USB control endpoint. It handles the low level USB protocol requests generated by the USB host controller and the commands for controlling the functional parameters of the FIFO in accordance with the USB 2.0 specification Section 9.

FIFO RX Buffer (128 bytes). Data sent from the USB host controller to the FIFO via the USB data OUT endpoint is stored in the FIFO RX (receive) buffer and is removed from the buffer by reading the contents of the FIFO using the RD# pin. (Rx relative to the USB interface).

FIFO TX Buffer (256 bytes). Data written into the FIFO using the WR pin is stored in the FIFO TX (transmit) Buffer. The USB host controller removes data from the FIFO TX Buffer by sending a USB request for data from the device data IN endpoint. (Tx relative to the USB interface).

FIFO Controller with Programmable High Drive. The FIFO Controller handles the transfer of data between the FIFO RX, the FIFO TX buffers and the external FIFO interface pins (D0 - D7). Additionally, the FIFO signals have a configurable high drive strength capability which is configurable in the EEPROM.

RESET Generator. The integrated Reset Generator Cell provides a reliable power-on reset to the device internal circuitry at power up. The RESET# input pin allows an external device to reset the FT245R. RESET# can be tied to VCC or left unconnected if not being used.

5 Devices Characteristics and Ratings

5.1 Absolute Maximum Ratings

The absolute maximum ratings for the FT232R devices are as follows. These are in accordance with the Absolute Maximum Rating System (IEC 60134). Exceeding these may cause permanent damage to the device.

Parameter	Value	Units
Storage Temperature	-65 to 150	°C
Floor Life (Out of Bag) At Factory Ambient (30°C / 60% Relative Humidity)	168 (IPC/JEDEC J-STD-033A MSL Level 3 Compliant)*	Hours
Ambient Temperature (Power Applied)	-40 to 85	°C
MTTF FT245RL	6607685	hours
MTTF FT245RQ	4464815	hours
VCC Supply Voltage	-0.5 to +6.00	V
DC Input Voltage – USBDP and USBDM	-0.5 to +3.8	V
DC Input Voltage – High Impedance Bidirectional	-0.5 to + (VCC +0.5)	V
DC Input Voltage – All Other Inputs	-0.5 to + (VCC +0.5)	V
DC Output Current – Outputs	24	mA
Power Dissipation (VCC = 5.25V)	500	mW

Table 5.1 Absolute Maximum Ratings

* If devices are stored out of the packaging beyond this time limit the devices should be baked before use. The devices should be ramped up to a temperature of +125°C and baked for up to 17 hours.

5.2 DC Characteristics

DC Characteristics (Ambient Temperature = -40°C to +85°C)

Parameter	Description	Minimum	Typical	Maximum	Units	Conditions
VCC1	VCC Operating Supply Voltage	4.0	---	5.25	V	Using Internal Oscillator
VCC1	VCC Operating Supply Voltage	3.3	---	5.25	V	Using External Crystal
VCC2	VCCIO Operating Supply Voltage	1.8	---	5.25	V	
Icc1	Operating Supply Current	---	15	---	mA	Normal Operation
Icc2	Operating Supply Current	50	70	100	µA	USB Suspend
3V3	3.3v regulator output	3.0	3.3	3.6	V	

Table 5.2 Operating Voltage and Current

Parameter	Description	Minimum	Typical	Maximum	Units	Conditions
Voh	Output Voltage High	3.2	4.1	4.9	V	I source = 2mA
Vol	Output Voltage Low	0.3	0.4	0.6	V	I sink = 2mA
Vin	Input Switching Threshold	1.0	1.2	1.5	V	**
VHys	Input Switching Hysteresis	20	25	30	mV	**

Table 5.3 UART and CBUS I/O Pin Characteristics (VCCIO = +5.0V, Standard Drive Level)

Parameter	Description	Minimum	Typical	Maximum	Units	Conditions
Voh	Output Voltage High	2.2	2.7	3.2	V	I source = 1mA
Vol	Output Voltage Low	0.3	0.4	0.5	V	I sink = 2mA
Vin	Input Switching Threshold	1.0	1.2	1.5	V	**
VHys	Input Switching Hysteresis	20	25	30	mV	**

Table 5.4 UART and CBUS I/O Pin Characteristics (VCCIO = +3.3V, Standard Drive Level)

Parameter	Description	Minimum	Typical	Maximum	Units	Conditions
Voh	Output Voltage High	2.1	2.6	2.8	V	I source = 1mA
Vol	Output Voltage Low	0.3	0.4	0.5	V	I sink = 2mA
Vin	Input Switching Threshold	1.0	1.2	1.5	V	**
VHys	Input Switching Hysteresis	20	25	30	mV	**

Table 5.5 UART and CBUS I/O Pin Characteristics (VCCIO = +2.8V, Standard Drive Level)

Parameter	Description	Minimum	Typical	Maximum	Units	Conditions
Voh	Output Voltage High	1.32	1.62	1.8	V	I source = 0.2mA
Vol	Output Voltage Low	0.06	0.1	0.18	V	I sink = 0.5mA
Vin	Input Switching Threshold	1.0	1.2	1.5	V	**
VHys	Input Switching Hysteresis	20	25	30	mV	**

Table 5.6 UART and CBUS I/O Pin Characteristics (VCCIO = +1.8V, Standard Drive Level)

Parameter	Description	Minimum	Typical	Maximum	Units	Conditions
Voh	Output Voltage High	3.2	4.1	4.9	V	I source = 6mA
Vol	Output Voltage Low	0.3	0.4	0.6	V	I sink = 6mA
Vin	Input Switching Threshold	1.0	1.2	1.5	V	**
VHys	Input Switching Hysteresis	20	25	30	mV	**

Table 5.7 UART and CBUS I/O Pin Characteristics (VCCIO = +5.0V, High Drive Level)

Parameter	Description	Minimum	Typical	Maximum	Units	Conditions
Voh	Output Voltage High	2.2	2.8	3.2	V	I source = 3mA
Vol	Output Voltage Low	0.3	0.4	0.6	V	I sink = 8mA
Vin	Input Switching Threshold	1.0	1.2	1.5	V	**
VHys	Input Switching Hysteresis	20	25	30	mV	**

Table 5.8 UART and CBUS I/O Pin Characteristics (VCCIO = +3.3V, High Drive Level)

Parameter	Description	Minimum	Typical	Maximum	Units	Conditions
Voh	Output Voltage High	2.1	2.6	2.8	V	I source = 3mA
Vol	Output Voltage Low	0.3	0.4	0.6	V	I sink = 8mA
Vin	Input Switching Threshold	1.0	1.2	1.5	V	**
VHys	Input Switching Hysteresis	20	25	30	mV	**

Table 5.9 UART and CBUS I/O Pin Characteristics (VCCIO = +2.8V, High Drive Level)

Parameter	Description	Minimum	Typical	Maximum	Units	Conditions
Voh	Output Voltage High	1.35	1.67	1.8	V	I source = 0.4mA
Vol	Output Voltage Low	0.12	0.18	0.35	V	I sink = 3mA
Vin	Input Switching Threshold	1.0	1.2	1.5	V	**
VHys	Input Switching Hysteresis	20	25	30	mV	**

Table 5.10 UART and CBUS I/O Pin Characteristics (VCCIO = +1.8V, High Drive Level)

** Only input pins have an internal 200K Ω pull-up resistor to VCCIO

Parameter	Description	Minimum	Typical	Maximum	Units	Conditions
Vin	Input Switching Threshold	1.3	1.6	1.9	V	
VHys	Input Switching Hysteresis	50	55	60	mV	

Table 5.11 RESET# and TEST Pin Characteristics

Parameter	Description	Minimum	Typical	Maximum	Units	Conditions
UVoh	I/O Pins Static Output (High)	2.8		3.6	V	RI = 1.5k Ω to 3V3OUT (D+) RI = 15K Ω to GND (D-)
UVol	I/O Pins Static Output (Low)	0		0.3	V	RI = 1.5k Ω to 3V3OUT (D+) RI = 15k Ω to GND (D-)
UVse	Single Ended Rx Threshold	0.8		2.0	V	
UCom	Differential Common Mode	0.8		2.5	V	
UVDif	Differential Input Sensitivity	0.2			V	
UDrvZ	Driver Output Impedance	26	29	44	Ohms	See Note 1

Table 5.12 USB I/O Pin (USBDP, USBDM) Characteristics

5.3 EEPROM Reliability Characteristics

The internal 1024 Bit EEPROM has the following reliability characteristics:

Parameter	Value	Units
Data Retention	10	Years
Write	10,000	Cycles
Read	Unlimited	Cycles

Table 5.13 EEPROM Characteristics

5.4 Internal Clock Characteristics

The internal Clock Oscillator has the following characteristics:

Parameter	Value			Unit
	Minimum	Typical	Maximum	
Frequency of Operation (see Note 1)	11.98	12.00	12.02	MHz
Clock Period	83.19	83.33	83.47	ns
Duty Cycle	45	50	55	%

Table 5.14 Internal Clock Characteristics

Note 1: Equivalent to +/-1667ppm

Parameter	Description	Minimum	Typical	Maximum	Units	Conditions
Voh	Output Voltage High	2.1	2.8	3.2	V	I source = 3mA
Vol	Output Voltage Low	0.3	0.4	0.6	V	I sink = 8mA
Vin	Input Switching Threshold	1.0	1.2	1.5	V	

Table 5.15 OSCI, OSCO Pin Characteristics – see Note 1

Note1: When supplied, the FT232R is configured to use its internal clock oscillator. These characteristics only apply when an external oscillator or crystal is used.

5.5 Thermal Characteristics

The FT245RL package has the following thermal characteristics:

Parameter	Value	Units	Conditions
Theta JA (θ_{JA})	55.82	°C/W	Still air
Theta JC (θ_{JC})	24.04	°C/W	

Table 5.16 FT245RL Thermal Characteristics

The FT245RQ package has the following thermal characteristics:

Parameter	Value	Units	Conditions
Theta JA (θ_{JA})	31.49	°C/W	Still air, center pad soldered to PCB, 9 vias to another plane
Theta JA (θ_{JA})	62.31	°C/W	Still air, center pad unsoldered
Theta JC (θ_{JC})		°C/W	

Table 5.17 FT245RQ Thermal Characteristics

6 USB Power Configurations

The following sections illustrate possible USB power configurations for the FT245R. The illustrations have omitted pin numbers for ease of understanding since the pins differ between the FT245RL and FT245RQ package options.

All USB power configurations illustrated apply to both package options for the FT245R device. Please refer to Section 3 for the package option pin-out and signal descriptions.

6.1 USB Bus Powered Configuration

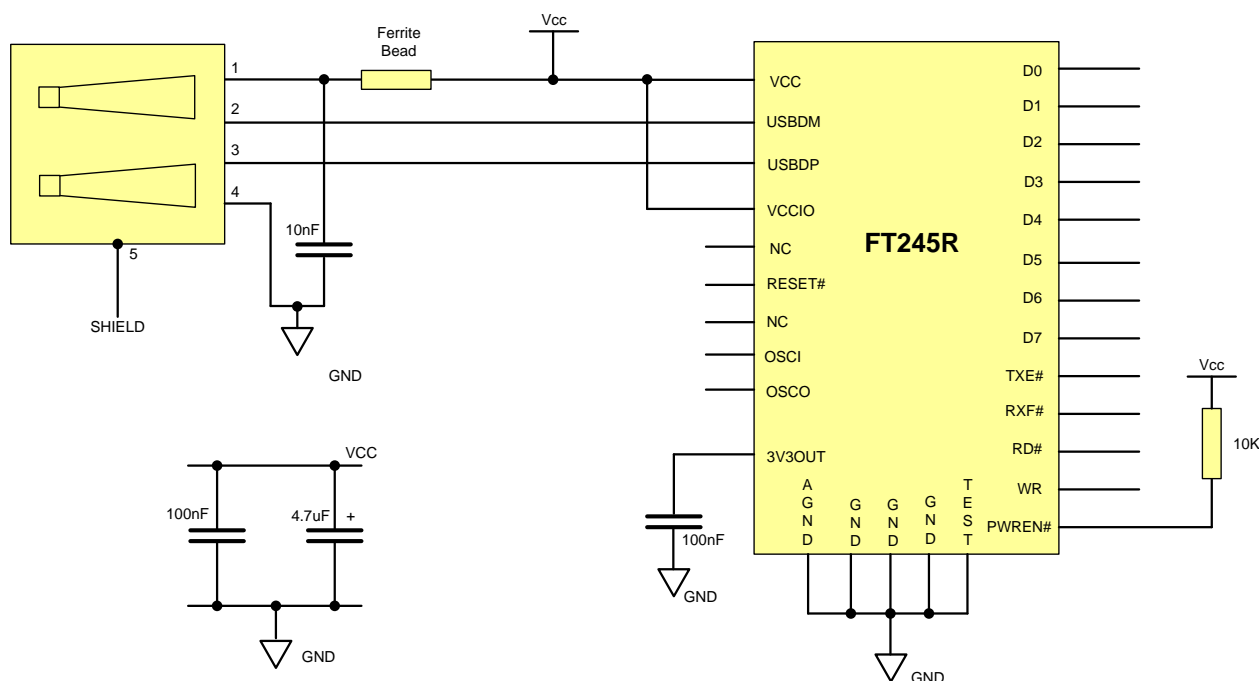


Figure 6.1 Bus Powered Configuration

Figure 6.1 illustrates the FT245R in a typical USB bus powered design configuration. A USB bus powered device gets its power from the USB bus. Basic rules for USB bus power devices are as follows –

- On plug-in to USB, the device should draw no more current than 100mA.
- In USB Suspend mode the device should draw no more than 2.5mA.
- A bus powered high power USB device (one that draws more than 100mA) should use the PWREN# to keep the current below 100mA on plug-in and 2.5mA on USB suspend.
- A device that consumes more than 100mA cannot be plugged into a USB bus powered hub.
- No device can draw more than 500mA from the USB bus.

The power descriptors in the internal EEPROM of the FT245R should be programmed to match the current drawn by the device.

A ferrite bead is connected in series with the USB power supply to reduce EMI noise from the FT245R and associated circuitry being radiated down the USB cable to the USB host. The value of the Ferrite Bead depends on the total current drawn by the application. A suitable range of Ferrite Beads is available from Steward (www.steward.com), for example Steward Part # MI0805K400R-10.

Note: If using PWREN#, the pin should be pulled to VCCIO using a 10kΩ resistor.

6.2 Self Powered Configuration

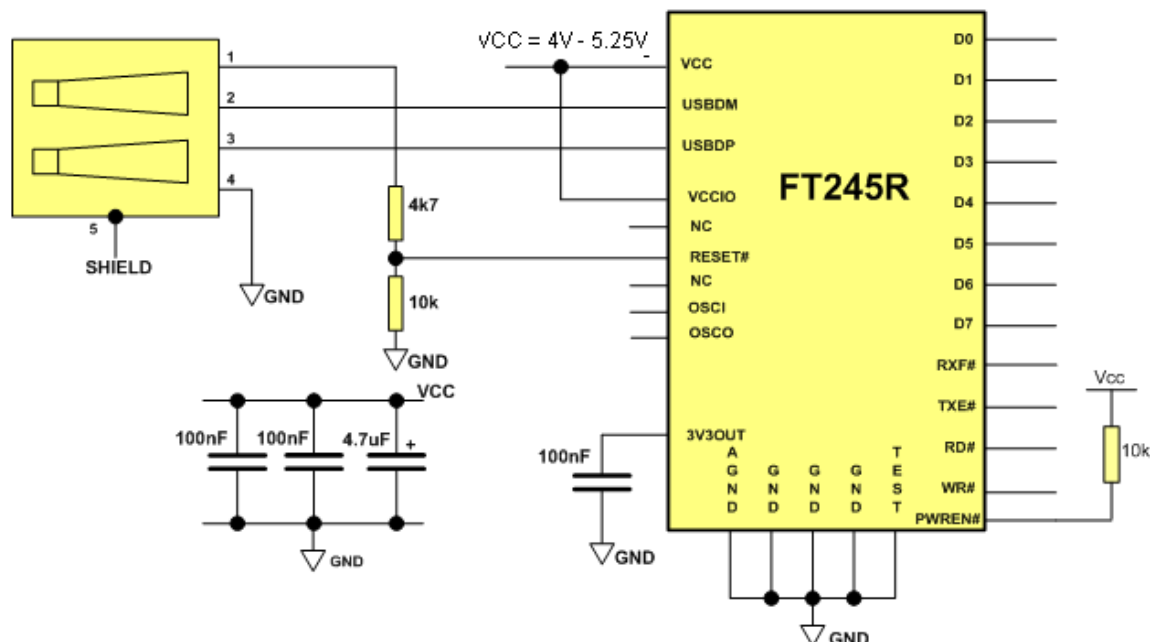


Figure 6.2 Self-Powered Configuration

Figure 6.2 illustrates the FT245R in a typical USB self-powered configuration. A USB self-powered device gets its power from its own power supply, VCC, and does not draw current from the USB bus. The basic rules for USB self-powered devices are as follows –

- i) A self-powered device should not force current down the USB bus when the USB host or hub controller is powered down.
- ii) A self-powered device can use as much current as it needs during normal operation and USB suspend as it has its own power supply.
- iii) A self-powered device can be used with any USB host, a bus powered USB hub or a self-powered USB hub.

The power descriptor in the internal EEPROM of the FT245R should be programmed to a value of zero (self-powered).

In order to comply with the first requirement above, the USB bus power (pin 1) is used to control the RESET# pin of the FT245R device. When the USB host or hub is powered up an internal 1.5kΩ resistor on USBDP is pulled up to +3.3V (generated using the 4K7 and 10k resistor network), thus identifying the device as a full speed device to the USB host or hub. When the USB host or hub is powered off, RESET# will be low and the FT245R is held in reset. Since RESET# is low, the internal 1.5kΩ resistor is not pulled up to any power supply (hub or host is powered down), so no current flows down USBDP via the 1.5kΩ pull-up resistor. Failure to do this may cause some USB host or hub controllers to power up erratically.

Figure 7.2 illustrates a self-powered design which has a +4V to +5.25V supply.

Note:

1. When the FT232R is in reset, the UART interface I/O pins are tri-stated. Input pins have internal 200kΩ pull-up resistors to VCCIO, so they will gently pull high unless driven by some external logic.
2. When using internal FT232R oscillator the VCC supply voltage range must be +4.0V to 5.25V.
3. When using external oscillator the VCC supply voltage range must be +3.3V to 5.25V
Any design which interfaces to +3.3 V or +1.8V would be having a +3.3V or +1.8V supply to VCCIO.

6.3 USB Bus Powered with Power Switching Configuration

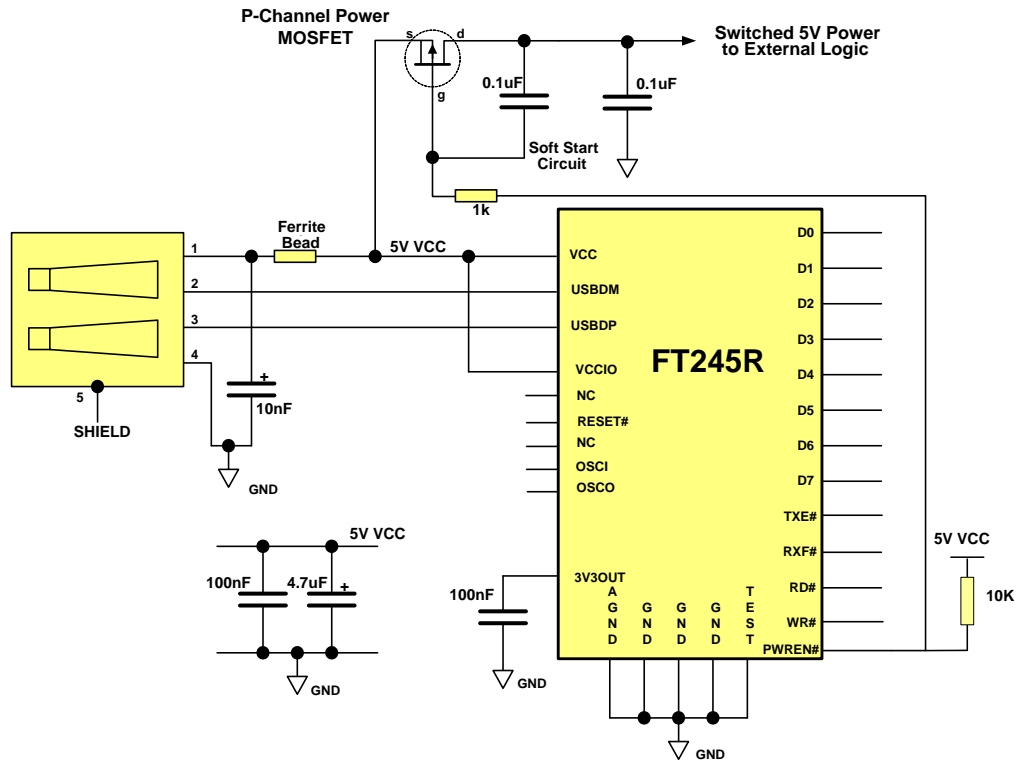


Figure 6.3 Bus Powered with Power Switching Configuration

A requirement of USB bus powered applications, is when in USB suspend mode the application draws a total current of less than 2.5mA. This requirement includes external logic. Some external logic has the ability to power itself down into a low current state by monitoring the PWREN# signal. For external logic that cannot power itself down in this way, the FT245R provides a simple but effective method of turning off power during the USB suspend mode.

Figure 6.3 shows an example of using a discrete P-Channel MOSFET to control the power to external logic. A suitable device to do this is an International Rectifier (www.irf.com) IRLML6402, or equivalent. It is recommended that a "soft start" circuit consisting of a 1kΩ series resistor and a 0.1μF capacitor is used to limit the current surge when the MOSFET turns on. Without the soft start circuit it is possible that the transient power surge, caused when the MOSFET switches on, will reset the FT245R or the USB host/hub controller. The soft start circuit example shown in Figure 6.3 powers up with a slew rate of approximately 12.5V/ms. Thus supply voltage to external logic transitions from GND to +5V in approximately 400 microseconds.

As an alternative to the MOSFET, a dedicated power switch IC with inbuilt "soft-start" can be used. A suitable power switch IC for such an application is the Micrel (www.micrel.com) MIC2025-2BM or equivalent.

With power switching controlled designs the following should be noted:

- The external logic to which the power is being switched should have its own reset circuitry to automatically reset the logic when power is re-applied when moving out of suspend mode.
- Set the Pull-down on Suspend option in the internal FT245R EEPROM.
- The PWREN# pin should be used to switch the power to the external circuitry.
- For USB high-power bus powered applications (one that consumes greater than 100mA, and up to 500mA of current from the USB bus), the power consumption of the application must be set in the Max Power field in the internal FT245R EEPROM. A high-power bus powered application uses the descriptor in the internal FT245R EEPROM to inform the system of its power requirements.
- PWREN# gets its VCC from VCCIO. For designs using 3V3 logic, ensure VCCIO is not powered down using the external logic. In this case use the +3V3OUT.

6.4 USB Bus Powered with Selectable External Logic Supply

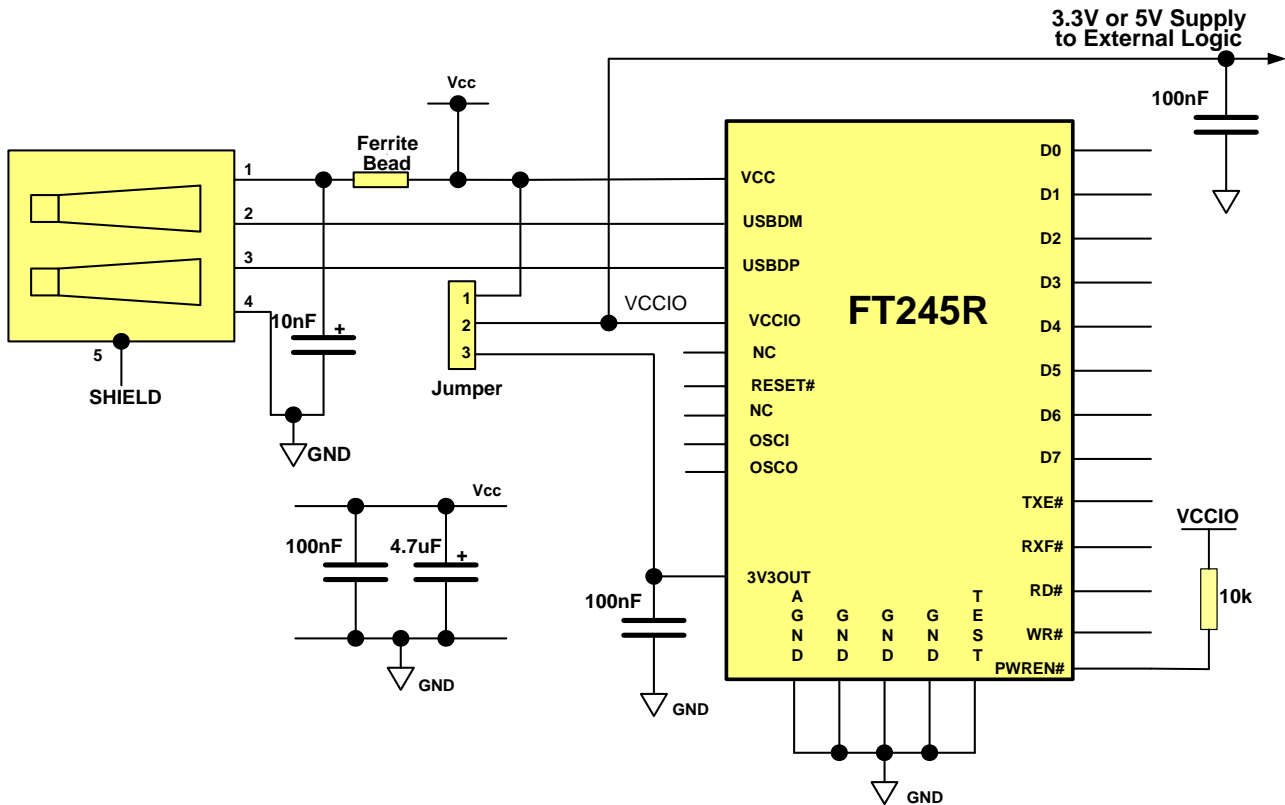


Figure 6.4 USB Bus Powered with +3.3V or +5V External Logic Power Supply

Figure 6.4 illustrates a USB bus power application with selectable external logic supply. The external logic can be selected between +3.3V and +5V using the jumper switch. This jumper is used to allow the FT245R to be interfaced with a +3.3V or +5V logic devices. The VCCIO pin is either supplied with +5V from the USB bus (jumper pins 1 and 2 connected), or from the +3.3V output from the FT245R 3V3OUT pin (jumper pins 2 and 3 connected). The supply to VCCIO is also used to supply external logic.

With bus powered applications, the following should be noted:

- To comply with the 2.5mA current supply limit during USB suspend mode, PWREN# or SLEEP# signals should be used to power down external logic in this mode. If this is not possible, use the configuration shown in Section 8.
- The maximum current sourced from the USB bus during normal operation should not exceed 100mA, otherwise a bus powered design with power switching (Section 6.3) should be used.

Another possible configuration could use a discrete low dropout (LDO) regulator which is supplied by the 5V on the USB bus to supply between +1.8V and +2.8V to the VCCIO pin and to the external logic. In this case VCC would be supplied with the +5V from the USB bus and the VCCIO would be supplied from the output of the LDO regulator. This results in the FT245R I/O pins driving out at between +1.8V and +2.8V logic levels.

or a USB bus powered application, it is important to consider the following when selecting the regulator:

- The regulator must be capable of sustaining its output voltage with an input voltage of +4.35V. An Low Drop Out (LDO) regulator should be selected.
- The quiescent current of the regulator must be low enough to meet the total current requirement of $\leq 2.5\text{mA}$ during USB suspend mode.

A suitable series of LDO regulators that meets these requirements is the MicroChip/Telecom (www.microchip.com) TC55 series of devices. These devices can supply up to 250mA current and have a quiescent current of under 1 μA .

7 Application Examples

The following sections illustrate possible applications of the FT245R. The illustrations have omitted pin numbers for ease of understanding since the pins differ between the FT245RL and FT245RQ package options.

7.1 USB to MCU FIFO Interface

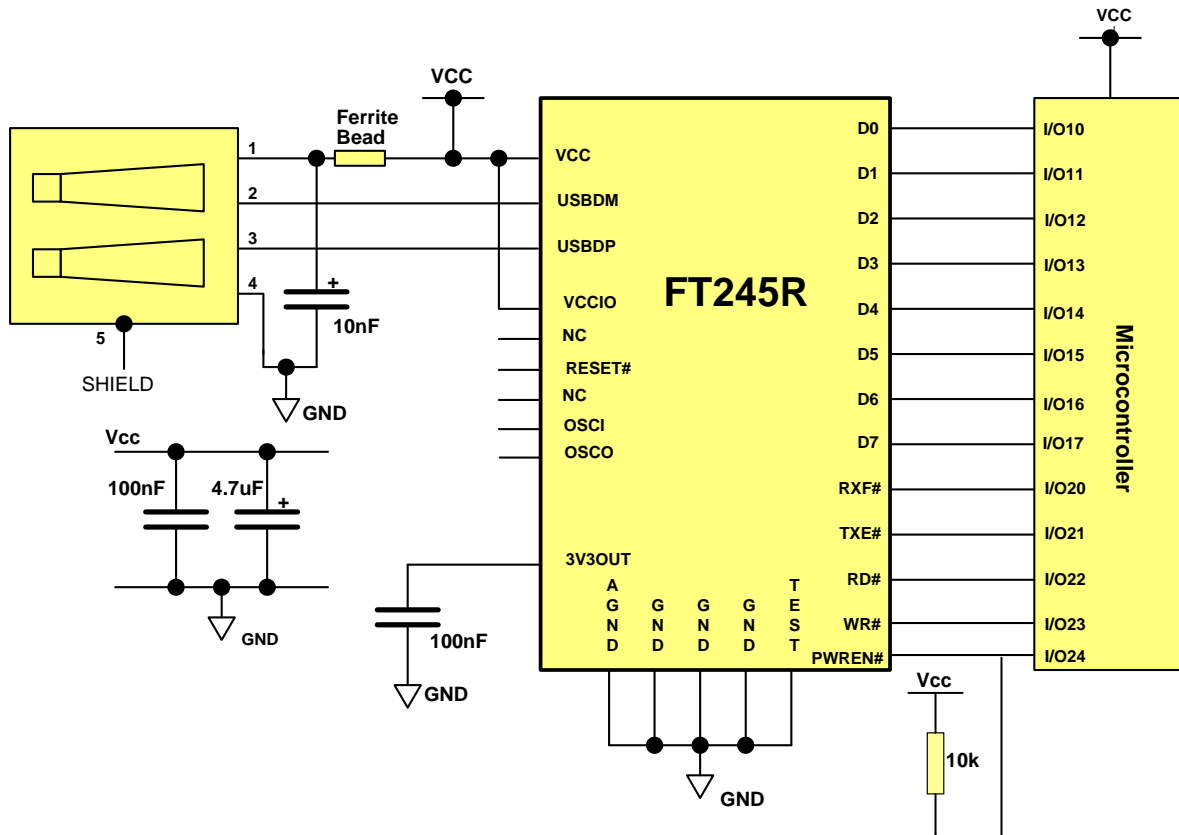


Figure 7.1 USB to MCU FIFO Interface

A typical example of using the FT245R as a USB to Microcontroller (MCU) FIFO interface is illustrated in Figure 7.1. This example uses two MCU I/O ports: one port (8 bits) to transfer data and the other port (4 or 5 bits) to monitor the TXE# and RXF# status bits and generate the RD# and WR strobes to the FT245R, when required.

Using PWREN# for this function is optional.

If the Remote Wakeup option is enabled in the internal EEPROM, during USB suspend mode RXF# becomes an input which can be used to wake up the USB host controller by strobing the pin low.

7.2 Using the External Oscillator

The FT245R defaults to operating using its own internal oscillator. This requires that the device is powered with VCC (min)=+4.0V. This supply voltage can be taken from the USB VBUS. Applications which require using an external oscillator, VCC= +3.3V must do so in the following order:

1. When device powered for the very first time, it must have VCC > +4.0V. This supply is available from the USB VBUS supply = +5.0V.
2. The EEPROM must then be programmed to enable external oscillator. This EEPROM modification cannot be done using the FTDI programming utility, MPROG and FT_PROG. The EEPROM can only be re-configured from a custom application. Please refer to the following applications note on how to do this:

[http://www.ftdichip.com/Documents/AppNotes/AN_100_Using_The_FT232_245R_With_External_Osc\(FT_000067\).pdf](http://www.ftdichip.com/Documents/AppNotes/AN_100_Using_The_FT232_245R_With_External_Osc(FT_000067).pdf)

3. The FT245R can then be powered from VCC=+3.3V and an external oscillator. This can be done using a link to switch the VCC supply.

The FT245R will fail to operate when the internal oscillator has been disabled, but no external oscillator has been connected.

8 Internal EEPROM Configuration

Following a power-on reset or a USB reset the FT245R will scan its internal EEPROM and read the USB configuration descriptors stored there. The default factory programmed values of the internal EEPROM are shown in Table 8.1 Default Internal EEPROM Configuration.

Parameter	Value	Notes
USB Vendor ID (VID)	0403h	FTDI default VID (hex)
USB Product ID (PID)	6001h	FTDI default PID (hex)
Serial Number Enabled?	Yes	
Serial Number	See Note	A unique serial number is generated and programmed into the EEPROM during device final test.
Pull down I/O Pins in USB Suspend	Disabled	Enabling this option will make the device pull down on the FIFO interface lines when in USB suspend mode (PWREN# is high).
Manufacturer Name	FTDI	
Product Description	FT245R USB FIFO	
Max Bus Power Current	90mA	
Power Source	Bus Powered	
Device Type	FT245R	
USB Version	0200	Returns USB 2.0 device description to the host. Note: The device is a USB 2.0 Full Speed device (12Mb/s) as opposed to a USB 2.0 High Speed device (480Mb/s).
Remote Wake Up	Enabled	Taking RXF# low will wake up the USB host controller from suspend in approximately 20 ms.
High Current I/Os	Disabled	Enables the high drive level on the FIFO data bus and control I/O pins.
Load VCP Driver	Enabled	Makes the device load the VCP driver interface for the device.

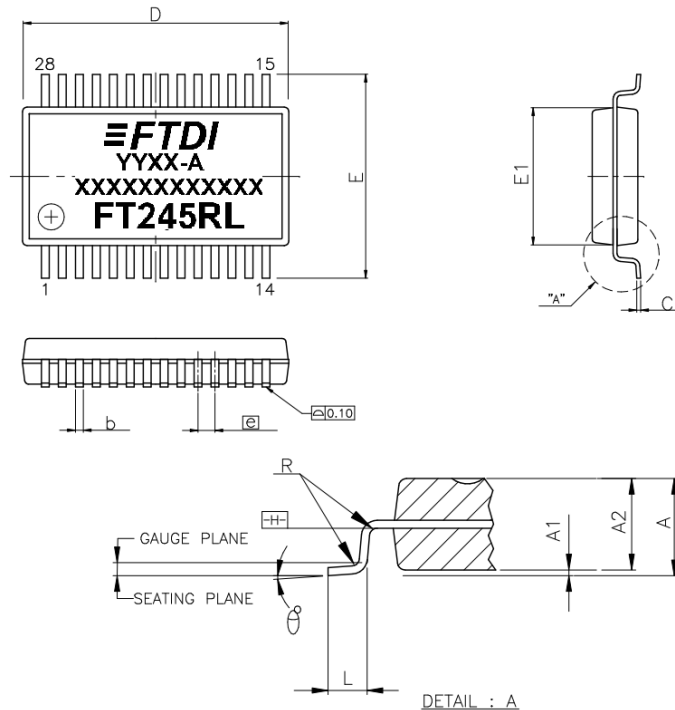
Table 8.1 Default Internal EEPROM Configuration

The internal EEPROM in the FT245R can be programmed over USB using the FTDI utility program MPROG and FT_PROG which can be downloaded from FTDI Utilities, on the FTDI website (www.ftdichip.com). Version 2.8a or later is required for the FT245R chip. Users who do not have their own USB Vendor ID but who would like to use a unique Product ID in their design can apply to FTDI for a free block of unique PIDs. Contact FTDI support for this service.

9 Package Parameters

The FT245R is available in two different packages. The FT245RL is the SSOP-28 option and the FT245RQ is the QFN-32 package option. The solder reflow profile for both packages is described in Section 9.3.

9.1 SSOP-28 Package Dimensions



SYMBOLS	MIN.	NOM.	MAX.
A	—	—	2.0
A1	0.05	—	—
A2	1.65	1.75	1.85
b	0.22	—	0.38
c	0.09	—	0.25
D	10.05	10.20	10.50
E	7.65	7.80	7.90
E1	5.00	5.30	5.60
e	0.65 BSC		
L	0.55	0.75	0.95
R	0.09	—	—
θ°	0°	4°	8°

UNIT : MM

NOTES :

1. JEDEC OUTLINE : MO-150 AH
2. "D" AND "E1" DIMENSIONS DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS, BUT DOES INCLUDE MOLD MISMATCH AND ARE MEASURED AT DATUM PLANE \overline{EE} , MOLD PARTING LINE. MOLD FLASH OR PROTRUSION SHALL NOT EXCEED 0.20 mm PER SIDE.
3. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION/INTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.13mm TOTAL IN EXCESS OF b DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR INTRUSION SHALL NOT REDUCE DIMENSION b BY MORE THAN 0.07mm AT LEAST MATERIAL CONDITION.

Figure 9.1 SSOP-28 Package Dimensions

The FT245RL is supplied in a RoHS compliant 28 pin SSOP package. The package is lead (Pb) free and uses a 'green' compound. The package is fully compliant with European Union directive 2002/95/EC.

This package is nominally 5.30mm x 10.20mm body (7.80mm x 10.20mm including pins). The pins are on a 0.65 mm pitch. The above mechanical drawing shows the SSOP-28 package.

All dimensions are in millimetres.

The date code format is **YYXX-A** where XX = 2 digit week number, YY = 2 digit year number, A = single letter corresponding to the revision of the device (e.g. A or B or C).

The code **XXXXXXXXXXXX** is the manufacturing LOT code. This only applies to devices manufactured after April 2009.

9.2 QFN-32 Package Dimensions

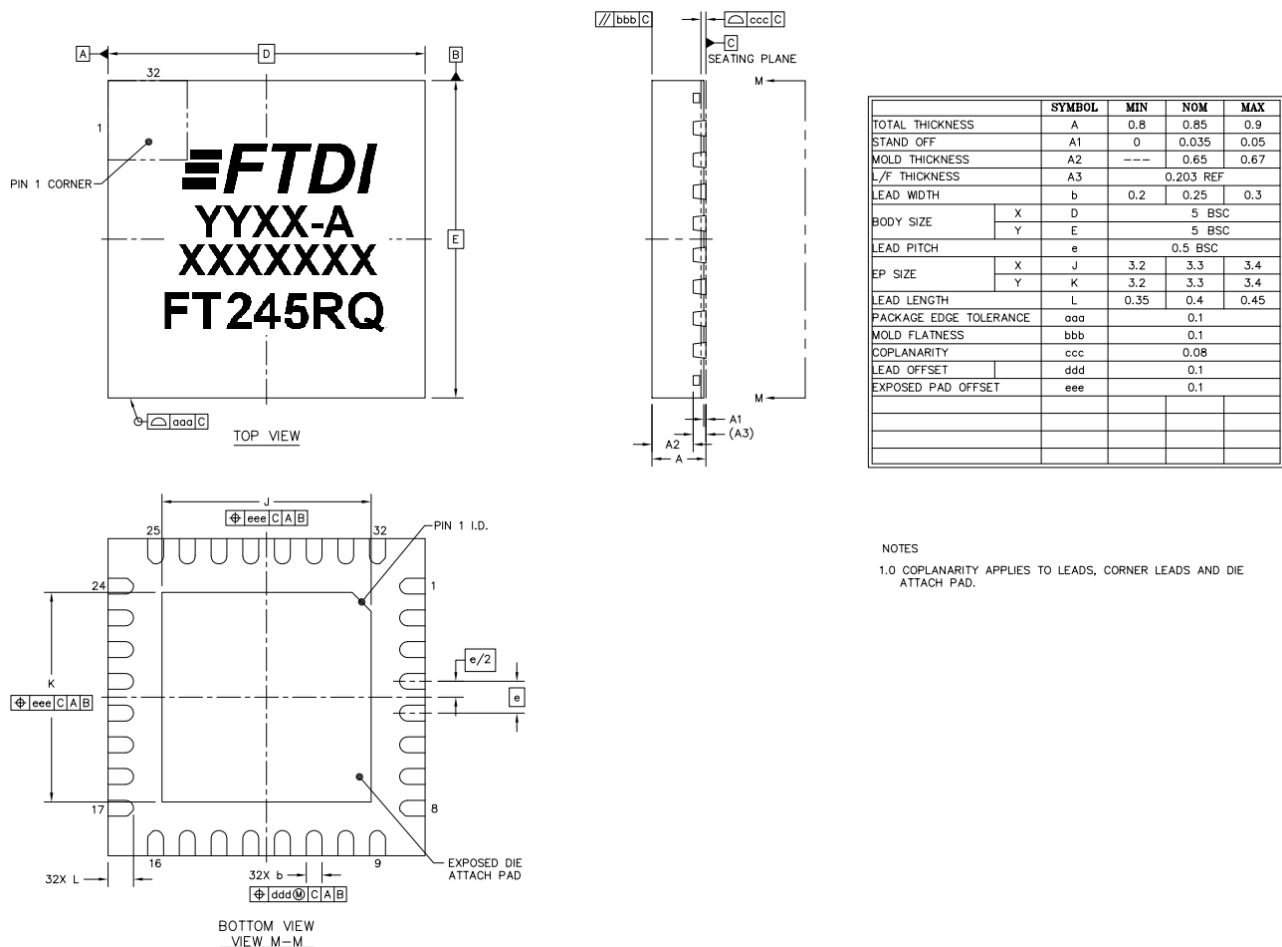


Figure 9.2 QFN-32 Package Dimensions

The FT245RQ is supplied in a RoHS compliant leadless QFN-32 package. The package is lead (Pb) free, and uses a 'green' compound. The package is fully compliant with European Union directive 2002/95/EC.

This package is nominally 5.00mm x 5.00mm. The solder pads are on a 0.50mm pitch. The above mechanical drawing shows the QFN-32 package. All dimensions are in millimetres.

The centre pad on the base of the FT245RQ is not internally connected, and can be left unconnected, or connected to ground (recommended).

The date code format is **YYXX-A** where XX = 2 digit week number, YY = 2 digit year number, A = single letter corresponding to the revision of the device (e.g. A or B or C).

The code **XXXXXXX** is the manufacturing LOT code. This only applies to devices manufactured after April 2009.

9.3 Solder Reflow Profile

The FT245R is supplied in Pb free 28 LD SSOP and QFN-32 packages. The recommended solder reflow profile for both package options is shown in 9.3.

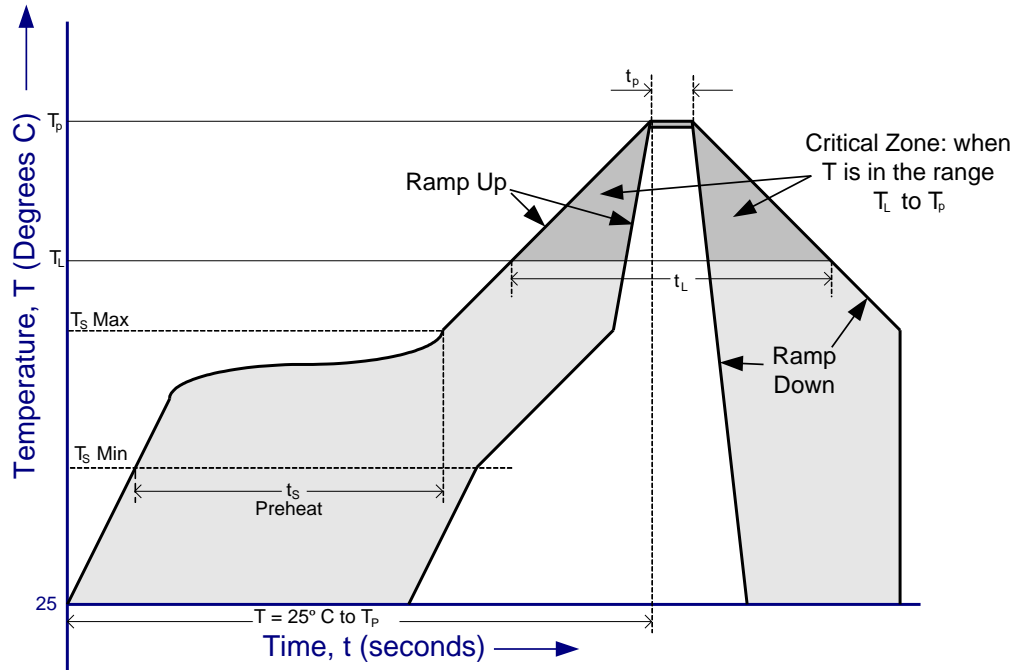


Figure 9.3 FT245R Solder Reflow Profile

The recommended values for the solder reflow profile are detailed in Table 9.1. Values are shown for both a completely Pb free solder process (i.e. the FT245R is used with Pb free solder), and for a non-Pb free solder process (i.e. the FT245R is used with non-Pb free solder).

Profile Feature	Pb Free Solder Process	Non-Pb Free Solder Process
Average Ramp Up Rate (T_s to T_p)	3°C / second Max.	3°C / Second Max.
Preheat - Temperature Min (T_s Min.) - Temperature Max (T_s Max.) - Time (t_s Min to t_s Max)	150°C 200°C 60 to 120 seconds	100°C 150°C 60 to 120 seconds
Time Maintained Above Critical Temperature T_L : - Temperature (T_L) - Time (t_L)	217°C 60 to 150 seconds	183°C 60 to 150 seconds
Peak Temperature (T_p)	260°C	240°C
Time within 5°C of actual Peak Temperature (t_p)	20 to 40 seconds	20 to 40 seconds
Ramp Down Rate	6°C / second Max.	6°C / second Max.
Time for $T = 25^\circ\text{C}$ to Peak Temperature, T_p	8 minutes Max.	6 minutes Max.

Table 9.1 Reflow Profile Parameter Values

10 Alternative Parts

The following list of parts are not all direct drop in replacements but offer similar features as an alternative to the FT245R. The FT-X series is the latest device family offering reduced power and pin count with additional features such as battery charge detection, while the Hi-Speed solution offers faster interfacing.

	FT245R	FT240X	FT232H
Description	Single channel USB to asynchronous FIFO	Single channel USB to asynchronous FIFO	Single channel USB to asynchronous FIFO (Need MTP to configure)
USB Speed	USB 2.0 full speed	USB 2.0 full speed	USB 2.0 hi-speed
UART Data Rates	1 Mbyte/s	1Mbyte/s	8 Mbyte/s
MTP for storing descriptors	Internal	Internal	External
Package options	32 pin QFN 28 pin SSOP	24 pin QFN 24 pin SSOP	48 pin QFN 48 pin LQFP
Datasheet	FT245R	FT234XD	FT232H

Table 10.1 FT245R Alternative Solutions

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Appendix A - References

Document References

http://www.ftdichip.com/Documents/AppNotes/AN232R-01_FT232RBitBangModes.pdf
http://www.ftdichip.com/Documents/AppNotes/AN_107_AdvancedDriverOptions_AN_000073.pdf
http://www.ftdichip.com/Documents/AppNotes/AN232R-02_FT232RChipID.pdf
http://www.ftdichip.com/Documents/AppNotes/AN_121_FTDI_Device_EEPROM_User_Area_Usage.pdf
http://www.ftdichip.com/Documents/AppNotes/AN_120_Aliasing_VCP_Baud_Rates.pdf
[http://www.ftdichip.com/Documents/AppNotes/AN_100_Using_The_FT232_245R_With_External_Osc\(FT_000067\).pdf](http://www.ftdichip.com/Documents/AppNotes/AN_100_Using_The_FT232_245R_With_External_Osc(FT_000067).pdf)
http://www.ftdichip.com/Resources/Utilities/AN_126_User_Guide_For_FT232_Factory%20test%20utility.pdf
http://www.ftdichip.com/Documents/AppNotes/AN232B-05_BaudRates.pdf
<http://www.ftdichip.com/Documents/InstallGuides.htm>

Acronyms & Abbreviations

Terms	Description
EEPROM	Electrically Erasable Programmable Read-Only Memory
FPGA	Field Programmable Gate Array
LED	Light Emitting Diode
MCU	Micro Controller Unit
PLD	Programmable Logic Device
QFN	Quad Flat No-leads
RoHS	Restriction of Hazardous Substances Directive
SIE	Serial Interface Engine
UART	Universal Asynchronous Receiver/Transmitter
USB	Universal Serial Bus
VCP	Virtual Communication Port

Appendix B - List of Figures and Tables

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Appendix C - Revision History

Document Title: FT245R USB FIFO IC Datasheet
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Revision	Changes	Date
Version 1.00	Initial Release	December 2005
Version 1.02	Minor revisions to datasheet release	December 2005
Version 1.03	Manufacturer ID added to default EEPROM data	January 2006
Version 1.04	Buffer Sizes Added	January 2006
Version 1.05	QFN-32 Package pad layout and solder paste diagrams added	January 2006
Version 2.00	Reformatted, added notes for 3.3V operation; Part numbers, TID, corrected; QFN Package drawing corrected. Added FIFO characteristics for +1.8V; Added MTTF data Corrected the input switching threshold and input hysteresis figures for VCCIO=+5V	June 2008
Version 2.01	Corrected the RX and TX Buffer data flow direction in the block Diagram Figure 2.1	July 2008
Version 2.02	Removed repeated section of table 8.1 Improved graphics on Figures 6.2, 6.3, 6.4 and 7.1 Add Packing details Changed USB suspend current spec from 500uA to 2.5m Corrected Figure 9.2 QFN dimensions.	August 2008
Version 2.03	Amended definition of FIFO TX and RX buffers to be consistent Updated company contact information	February 2009
Version 2.04	Corrected Tape and Reel quantities Added LOT numbers to the device markings. Clarified VCC operation and added section headed "Using an external Oscillator" Added 3V3 regulator output tolerance	April 2009
Version 2.05	Corrected Tx and RX buffer sizes on front page	June 2009
Version 2.06	Additional Dimensions added to QFN Solder Profile	June 2009
Version 2.07	Changed label 'D6' to 'D7' (pin 3) on FT245RQ schematic symbol Updated to latest TID number Added Window 7 support	October 2009

Revision	Changes	Date
Version 2.08	Modified package dimensions to 5.0 x 5.0 +/-0.075mm and Solder paste diagram to 2.50 x 2.50 +/-0.0375mm Added FT_PROG utility references Added Appendix A-references Corrected USB-IF TID	December 2009
Version 2.09	Updated section 6.2, Figure 6.2 and the note, Updated section 5.3, Table 5.13, EEPROM data retention time	May 2010
Version 2.10	Removed RD# and WR# references on BitBang modes Corrected US Support email address. Added USB Compliance logo	July 2010
Version 2.11	Updated USB-IF TID for Rev C	April 2011
Version 2.12	Corrected TID for Rev C	April 2011
Version 2.13	Added Thermal Characteristics (Section 5.5) Added document information and feedback to revision history Added section 10 on alternative parts	February 2015
Version 2.14	Updated Fig. 3.2 QFN-32 Package Pin Out and schematic symbol Updated Fig. 9.1 SSOP-28 Package Dimensions Updated Fig. 9.2 QFN-32 Package Dimensions Deleted QFN-32 Package Typical Pad Layout and QFN-32 Package Typical Solder Paste Diagram sections.	2019-04-04
Version 2.15	Added note about revision letter in the package marking pages (Package Parameters section 9)	2020-05-21